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1 Purpose and Scope

1.1 Purpose

To document the materials composition declaration for QFN packages for Encore products manufactured from Carsem and UTAC.

1.2 Scope

Products covered: SiT3807, SiT3808, SiT3809, SiT8208, SiT8209, SiT5000, SiT5001, SiT5002, SiT5003, SiT5004, SiT9120, SiT9121, SiT9122, SiT9156, SiT3821, SiT3822, SiT5021, SiT5022, SiT5023, SiT5024, SiT3921, SiT3922, SiT3621, SiT3622, SiT3651 and SiT3652.

Packages covered: 4QFN 2.7 mm x 2.4 mm (2520-G), 3.2 mm x 2.5 mm, 5.0 mm x 3.2 mm, 7.0 mm x 5.0 mm, 6QFN 3.2 mm x 2.5 mm, 6QFN 5.0 mm x 3.2 mm and 6QFN 7.0 mm x 5.0 mm packages.

2 Reference Documents

2.1 EU RoHS Directive 2002/95/EC and amendments

2.2 Internal References

2.2.1 QI-1 SiTime green partner and RoHS/Green Compliance

2.2.2 QI-73 RoHS Certificate for Homogeneous Materials in QFN Packages

2.2.3 QI-21 RoHS Certificate for CMOS die TSMC

2.2.4 QI-22 RoHS Certificate for MEMS die Tower Jazz

2.2.5 QI-77 RoHS Certificate for MEMS die Bosch

3 Material Composition Declaration

The components (homogeneous materials) contained in the QFN packages used for Encore products are listed in the tables listed below. It should be noted that contents declared are from engineering estimates based on the MSDS and material C of C from material vendors; it is expected to have rounding/estimation errors. Component weight is based on assembly of generic parts.

- 3.1 As per industry standard practice (JEDEC Standard JESD46), the information provided in this document will be updated only when any major change in the material composition is implemented. Therefore, annual update is not necessary.
- 3.2 [Table 1](#) Composition table for UTAC 3.2 mm x 2.5 mm 4QFN Package
- 3.3 [Table 2](#) Composition table for UTAC 5.0 mm x 3.2 mm 4QFN Package
- 3.4 [Table 3](#) Composition table for UTAC 7.0 mm x 5.0 mm 4QFN Package
- 3.5 [Table 4](#) Composition table for Carsem 3.2 mm x 2.5 mm 4QFN Package
- 3.6 [Table 5](#) Composition table for Carsem 5.0 mm x 3.2 mm 4QFN Package
- 3.7 [Table 6](#) Composition table for Carsem 5.0 mm x 3.2 mm 6QFN Package
- 3.8 [Table 7](#) Composition table for UTAC 7.0 mm x 5.0 mm 6QFN Package
- 3.9 [Table 8](#) Composition table for Carsem 2.7 mm x 2.4 mm 4QFN Package (Package 2520-G)
- 3.10 [Table 9](#) Composition table for Carsem 3.2 mm x 2.5 mm 6QFN Package

Table 1:
Base Products –
SiT3807, SiT3808, SiT3809, SiT8208, SiT8209, SiT5000, SiT5001, SiT5002, SiT5003, SiT5004

4L QFN 3.2 mm x 2.5 mm PACKAGE TABLE OF MATERIAL DECLARATION – UTAC

No.	Name of the Component	Material Type	Component Weight, mg	Materials Analysis (element)	CAS Number	Element Weight, mg	Element wt% of Component	Element wt % of Package
1	Leadframe	C194 Alloy	5.006	Copper	7440-50-8	4.882	97.52	27.74
				Iron	7439-89-6	0.118	2.36	0.67
				Zinc	7440-66-6	0.006	0.12	0.03
1a	Plating	NiPdAu	0.068	Nickel	7440-02-0	0.065	95.50	0.37
				Palladium	7440-05-3	0.002	3.00	0.01
				Gold	7440-57-5	0.001	1.50	0.01
2	Die 1	CMOS Die	1.075	Si	7440-21-3	1.075	100.00	6.11
3	Die 2	MEMS Die	0.082	Si	7440-21-3	0.082	100.00	0.47
4	Die attach material 1	Non-Conductive epoxy	0.269	Fused silica	60676-86-0	0.188	69.89	1.07
				Epoxy resin	Proprietary	0.041	15.24	0.23
				Bisphenol A diglycidyl ether resin	25068-38-6	0.021	7.81	0.12
				Additive	Proprietary	0.019	7.06	0.11
5	Die attach material 2	Conductive epoxy	0.173	Silver	7440-22-4	0.137	79.19	0.78
				Acrylate	Proprietary	0.031	17.92	0.18
				Resin	Proprietary	0.004	2.31	0.02
				Additive	Proprietary	0.001	0.58	0.01
6	Wire	Gold	0.108	Au	7440-57-5	0.108	100.00	0.61
7	Encapsulation	Epoxy Resin	10.816	Fused silica	60676-86-0	9.789	90.50	55.62
				Epoxy resin	Proprietary	0.508	4.70	2.89
				Phenol resin	Proprietary	0.508	4.70	2.89
				Carbon black	1333-86-4	0.011	0.10	0.06
Total Package Weight, mg:			17.597					

Table 2:
Base Products –
SiT3807, SiT3808, SiT3809, SiT8208, SiT8209, SiT5000, SiT5001, SiT5002, SiT5003, SiT5004

4L QFN 5.0 mm x 3.2 mm PACKAGE TABLE OF MATERIAL DECLARATION – UTAC

No.	Name of the Component	Material Type	Component Weight, mg	Materials Analysis (element)	CAS Number	Element Weight, mg	Element wt% of Component	Element wt % of Package
1	Leadframe	C194 Alloy	15.082	Copper	7440-50-8	14.709	97.52	36.92
				Iron	7439-89-6	0.354	2.35	0.89
				Zinc	7440-66-6	0.019	0.13	0.05
1a	Plating	NiPdAu	0.208	Nickel	7440-02-0	0.197	95.00	0.49
				Palladium	7440-05-3	0.007	3.30	0.02
				Gold	7440-57-5	0.004	1.70	0.01
2	Die 1	CMOS Die	1.075	Si	7440-21-3	1.075	100.00	2.7
3	Die 2	MEMS Die	0.082	Si	7440-21-3	0.082	100.00	0.21
4	Die attach material 1	Non-Conductive epoxy	0.343	Fused silica	60676-86-0	0.24	69.97	0.6
				Epoxy resin	Proprietary	0.052	15.16	0.13
				Bisphenol A diglycidyl ether resin	25068-38-6	0.027	7.87	0.07
				Additive	Proprietary	0.024	7.00	0.06
5	Die attach material 2	Conductive epoxy	0.168	Silver	7440-22-4	0.133	79.16	0.33
				Acrylate	Proprietary	0.030	17.86	0.08
				Resin	Proprietary	0.004	2.38	0.01
				Additive	Proprietary	0.001	0.60	0
6	Wire	Gold	0.146	Au	7440-57-5	0.146	100.00	0.37
7	Encapsulation	Epoxy Resin	22.729	Silica fused	60676-86-0	20.57	90.50	51.64
				Epoxy resin	Proprietary	1.068	4.70	2.68
				Phenol resin	Proprietary	1.068	4.70	2.68
				Carbon black	1333-86-4	0.023	0.10	0.06
Total Package Weight, mg:			39.8330					

Table 3:
Base Products –
SiT3807, SiT3808, SiT3809, SiT8208, SiT8209, SiT5000, SiT5001, SiT5002, SiT5003, SiT5004
4L QFN 7.0 mm x 5.0 mm NO EXPOSED PAD PACKAGE TABLE OF MATERIAL DECLARATION – UTAC

No.	Name of the Component	Material Type	Component Weight, mg	Materials Analysis (element)	CAS Number	Element wt., mg	Element wt% of Component	Element wt % of Package
1	Leadframe	C194 Alloy	35.297	Copper	7440-50-8	34.422	97.52	41.26
				Iron	7439-89-6	0.829	2.35	0.99
				Zinc	7440-66-6	0.046	0.13	0.06
1a	Plating	NiPdAu	0.486	Nickel	7440-02-0	0.458	94.24	0.55
				Palladium	7440-05-3	0.017	3.50	0.02
				Gold	7440-57-5	0.011	2.26	0.01
2	Die 1	CMOS Die	1.075	Si	7440-21-3	1.075	100.00	1.29
3	Die 2	MEMS Die	0.082	Si	7440-21-3	0.082	100.00	0.10
4	Die attach material 1	Non-Conductive epoxy	0.276	Fused silica	60676-86-0	0.193	69.97	0.23
				Epoxy resin	Proprietary	0.042	15.16	0.05
				Bisphenol A diglycidyl ether resin	25068-38-6	0.022	7.87	0.03
				Additive	Proprietary	0.019	7.00	0.02
5	Die attach material 2	Conductive epoxy	0.167	Silver	7440-22-4	0.132	79.16	0.16
				Acrylate	Proprietary	0.030	17.86	0.04
				Resin	Proprietary	0.004	2.38	0.00
				Additive	Proprietary	0.001	0.60	0.00
6	Wire	Gold	0.466	Au	7440-57-5	0.466	100.00	0.56
7	Encapsulation	Epoxy Resin	45.579	Fused silica	60676-86-0	41.249	90.50	49.44
				Epoxy resin	Proprietary	2.142	4.70	2.57
				Phenol resin	Proprietary	2.142	4.70	2.57
				Carbon black	1333-86-4	0.046	0.1	0.05
Total Package Weight, mg:			83.428					

Table 4:
Base Products –
SiT3807, SiT3808, SiT3809, SiT8208, SiT8209, SiT5000, SiT5001, SiT5002, SiT5003, SiT5004

4L QFN 3.2 mm x 2.5 mm PACKAGE TABLE OF MATERIAL DECLARATION – Carsem

No.	Name of the Component	Material Type	Component Weight, mg	Materials Analysis (element)	CAS Number	Element Weight, mg	Element wt% of Compon	Element wt % of Package
1	Leadframe	C194 Alloy	5.448	Copper	7440-50-8	5.317	97.60	32.12
				Iron	7439-89-6	0.127	2.33	0.77
				Zinc	7440-66-6	0.004	0.07	0.02
1a	Plating	NiPdAu	0.072	Nickel	7440-02-0	0.067	93.06	0.40
				Palladium	7440-05-3	0.003	4.17	0.02
				Gold	7440-57-5	0.002	2.78	0.01
2	Die 1	CMOS Die	1.075	Si	7440-21-3	1.075	100.00	6.49
3	Die 2	MEMS Die	0.082	Si	7440-21-3	0.082	100.00	0.50
4	Die attach material 1	Non-Conductive epoxy	0.171	Aluminium oxide	1344-28-1	0.054	31.58	0.33
				Carbinol acetate	112-15-2	0.037	21.64	0.22
				Epoxy Cresol Novolac Resin	29690-82-2	0.031	18.13	0.19
				CP Bisph. A diglycidyl ether+Bisph. A	25036-25-3	0.017	9.94	0.10
				Bisphenol A diglycidyl ether resin	25068-38-6	0.009	5.26	0.05
				Dapsone	80-08-0	0.009	5.26	0.05
				Additive	Proprietary	0.014	8.19	0.08
5	Die attach material 2	Conductive epoxy	0.030	Silver	7440-22-4	0.022	74.00	0.13
				Acrylate	Proprietary	0.006	20.00	0.04
				Resin	Proprietary	0.001	3.00	0.01
				Additive	Proprietary	0.001	3.00	0.01
6	Wire	Gold	0.155	Au	7440-57-5	0.155	100.00	0.94
7	Encapsulation	Epoxy Resin	9.520	Fused silica	60676-86-0	8.913	93.62	53.84
				Epoxy resin	Proprietary	0.288	3.03	1.74
				Phenol resin	Proprietary	0.288	3.03	1.74
				Carbon black	1333-86-4	0.030	0.32	0.18
Total Package Weight, mg:			16.553					

Table 5:
Base Products –
SiT3807, SiT3808, SiT3809, SiT8208, SiT8209, SiT5000, SiT5001, SiT5002, SiT5003, SiT5004

4L QFN 5.0 mm x 3.2 mm PACKAGE TABLE OF MATERIAL DECLARATION – Carsem

No.	Name of the Compone	Material Type	Component Weight, mg	Materials Analysis (element)	CAS Number	Element Weight, mg	Element wt% of Compon	Element wt % of Package
1	Leadframe	C194 Alloy	10.759	Copper	7440-50-8	10.500	97.59	31.90
				Iron	7439-89-6	0.251	2.33	0.76
				Zinc	7440-66-6	0.008	0.07	0.02
1a	Plating	NiPdAu	0.142	Nickel	7440-02-0	0.132	92.96	0.40
				Palladium	7440-05-3	0.006	4.23	0.02
				Gold	7440-57-5	0.004	2.82	0.01
2	Die 1	CMOS Die	1.075	Si	7440-21-3	1.075	100.00	3.27
3	Die 2	MEMS Die	0.082	Si	7440-21-3	0.082	100.00	0.25
4	Die attach material 1	Non-Conductive epoxy	0.1711	Aluminium oxide	1344-28-1	0.0547	31.97	0.17
				Carbinol acetate	112-15-2	0.0376	21.98	0.11
				Epoxy Cresol Novolac Resin	29690-82-2	0.0308	18.00	0.09
				CP Bisph. A diglycidyl ether+Bisph. A	25036-25-3	0.0171	9.99	0.05
				Bisphenol A diglycidyl ether resin	25068-38-6	0.0086	5.03	0.03
				Dapsone	80-08-0	0.0086	5.03	0.03
5	Die attach material 2	Conductive epoxy	0.030	Silver	7440-22-4	0.022	73.33	0.07
				Acrylate	Proprietary	0.006	20.00	0.02
				Resin	Proprietary	0.001	3.33	0.00
				Additive	Proprietary	0.001	3.33	0.00
6	Wire	Gold	0.155	Au	7440-57-5	0.155	100.00	0.47
7	Encapsulation	Epoxy Resin	20.500	Fused silica	60676-86-0	19.192	93.62	58.31
				Epoxy resin	Proprietary	0.621	3.03	1.89
				Phenol resin	Proprietary	0.621	3.03	1.89
				Carbon black	1333-86-4	0.066	0.32	0.20
Total Package Weight, mg:			32.9141					

Table 6:

Base Products –

**SiT3807, SiT3808, SiT3809, SiT8208, SiT8209, SiT5000, SiT5001, SiT5002, SiT5003, SiT5004
SiT9120, SiT9121, SiT9122, SiT9156, SiT3821, SiT3822, SiT5021, SiT5022, SiT5023, SiT5024,
SiT3907, SiT3921, SiT3922, SiT3621, SiT3622, SiT3651, SiT3652**

6L QFN 5.0 mm x 3.2 mm PACKAGE TABLE OF MATERIAL DECLARATION – Carsem

No.	Name of the Component	Material Type	Component Weight, mg	Materials Analysis (element)	CAS Number	Element Weight, mg	Element wt % of Component	Element wt % of Package
1	Leadframe	C194 Alloy	8.369	Copper	7440-50-8	8.168	97.60	26.29
				Iron	7439-89-6	0.195	2.33	0.63
				Zinc	7440-66-6	0.006	0.07	0.02
1a	Plating	NiPdAu	0.111	Nickel	7440-02-0	0.103	92.79	0.33
				Palladium	7440-05-3	0.005	4.50	0.02
				Gold	7440-57-5	0.003	2.70	0.01
2	Die 1	CMOS Die	1.075	Si	7440-21-3	1.075	100.00	3.46
3	Die 2	MEMS Die	0.082	Si	7440-21-3	0.082	100.00	0.26
4	Die attach material 1	Non-Conductive epoxy	0.1711	Aluminium oxide	1344-28-1	0.0547	31.97	0.18
				Carbinol acetate	112-15-2	0.0376	21.98	0.12
				Epoxy Cresol Novolac Resin	29690-82-2	0.0308	18.00	0.10
				CP Bisph. A diglycidyl ether+Bisph. A	25036-25-3	0.0171	9.99	0.06
				Bisphenol A diglycidyl ether resin	25068-38-6	0.0086	5.03	0.03
				Dapsone	80-08-0	0.0086	5.03	0.03
				Additive	Proprietary	0.0137	8.01	0.04
5	Die attach material 2	Conductive epoxy	0.030	Silver	7440-22-4	0.022	73.33	0.07
				Acrylate	Proprietary	0.006	20.00	0.02
				Resin	Proprietary	0.001	3.33	0.00
				Additive	Proprietary	0.001	3.33	0.00
6	Wire	Gold	0.155	Au	7440-57-5	0.155	100.00	0.50
7	Encapsulation	Epoxy Resin	21.079	Fused silica	60676-86-0	19.734	93.62	63.51
				Epoxy resin	Proprietary	0.639	3.03	2.06
				Phenol resin	Proprietary	0.639	3.03	2.06
				Carbon black	1333-86-4	0.067	0.32	0.22
Total Package Weight, mg:			31.0721					

Table 7:

Base Products –

**SiT3807, SiT3808, SiT3809, SiT8208, SiT8209, SiT5000, SiT5001, SiT5002, SiT5003, SiT5004
SiT9120, SiT9121, SiT9122, SiT9156, SiT3821, SiT3822, SiT5021, SiT5022, SiT5023, SiT5024,
SiT3921, SiT3922, SiT3621, SiT3622, SiT3651, SiT3652**

6L QFN 7.0 mm x 5.0 mm PACKAGE TABLE OF MATERIAL DECLARATION – UTAC

No.	Name of the Component	Material Type	Component Weight, mg	Materials Analysis (element)	CAS Number	Element wt., mg	Element wt% of Component	Element wt % of Package
1	Leadframe	C194 Alloy	30.0500	Copper	7440-50-8	29.304760	97.52	35.48
				Iron	7439-89-6	0.7061750	2.35	0.85
				Zinc	7440-66-6	0.0390650	0.13	0.05
1a	Plating	NiPdAu	0.9950	Nickel	7440-02-0	0.945250	94.24	1.14
				Palladium	7440-05-3	0.0328350	3.50	0.04
				Gold	7440-57-5	0.0169150	2.26	0.02
2	Die 1	CMOS Die	1.0750	Si	7440-21-3	1.0750	100.00	1.30
3	Die 2	MEMS Die	0.0820	Si	7440-21-3	0.0820	100.00	0.10
4	Die attach material 1	Non-Conductive epoxy	0.2760	Fused silica	60676-86-0	0.19311720	69.97	0.23
				Epoxy resin	Proprietary	0.04184160	15.16	0.05
				Glycol ethers	25068-38-6	0.02172120	7.87	0.03
				Additive	Proprietary	0.019320	7.00	0.02
5	Die attach material 2	Conductive epoxy	0.1670	Silver	7440-22-4	0.13219720	79.16	0.16
				Acrylate	Proprietary	0.02982620	17.86	0.04
				Resin	Proprietary	0.00397460	2.38	0.00
				Additive	Proprietary	0.0010	0.60	0.00
6	Wire	Gold	0.3330	Au	7440-57-5	0.3330	100.00	0.40
7	Encapsulation	Epoxy Resin	49.6390	Fused silica	60676-86-0	44.9232950	90.50	54.39
				Epoxy resin	Proprietary	2.3330330	4.70	2.82
				Phenol resin	Proprietary	2.3330330	4.70	2.82
				Carbon black	1333-86-4	0.0496390	0.1	0.06
Total Package Weight, mg:			82.617					

Table 8:
Base Products –
SiT3807, SiT3808, SiT3809, SiT8208, SiT8209, SiT5000, SiT5001, SiT5002, SiT5003, SiT5004

4L QFN 2.5 mm x 2.0 mm PACKAGE TABLE OF MATERIAL DECLARATION – Carsem

No.	Name of the Component	Material Type	Component Weight, mg	Materials Analysis (element)	CAS Number	Element Weight, mg	Element wt% of Component	Element wt % of Package
1	Leadframe	C194 Alloy	3.850	Copper	7440-50-8	3.757	97.58	28.94
				Iron	7439-89-6	0.090	2.34	0.69
				Zinc	7440-66-6	0.003	0.08	0.02
1a	Plating	NiPdAu	0.051	Nickel	7440-02-0	0.046	90.20	0.35
				Palladium	7440-05-3	0.003	5.88	0.02
				Gold	7440-57-5	0.002	3.92	0.02
2	Die 1	CMOS Die	1.230	Si	7440-21-3	1.230	100.00	9.48
3	Die 2	MEMS Die	0.090	Si	7440-21-3	0.090	100.00	0.69
4	Die attach material 1	Non-Conductive epoxy	0.180	Aluminium oxide	1344-28-1	0.058	32.22	0.45
				Carbinol acetate	112-15-2	0.040	22.22	0.31
				Epoxy Cresol Novolac Resin	29690-82-2	0.032	17.78	0.25
				CP Bisph. A diglycidyl ether+Bisph. A	25036-25-3	0.018	10.00	0.14
				Bisphenol A diglycidyl ether resin	25068-38-6	0.009	5.00	0.07
				Dapsone	80-08-0	0.009	5.00	0.07
Additive	Proprietary	0.014	7.78	0.11				
5	Die attach material 2	Conductive epoxy	0.040	Silver	7440-22-4	0.030	75.00	0.23
				Acrylate	Proprietary	0.008	20.00	0.06
				Resin	Proprietary	0.001	2.50	0.01
				Additive	Proprietary	0.001	2.50	0.01
6	Wire	Gold	0.110	Au	7440-57-5	0.110	100.00	0.85
7	Encapsulation	Epoxy Resin	7.430	Fused silica	60676-86-0	6.956	93.62	53.59
				Epoxy resin	Proprietary	0.225	3.03	1.73
				Phenol resin	Proprietary	0.225	3.03	1.73
				Carbon black	1333-86-4	0.024	0.32	0.18
Total Package Weight, mg:			12.9810					

Table 9:

Base Products –

SiT9120, SiT9121, SiT9122, SiT9156, SiT3821, SiT3822, SiT5021, SiT5022, SiT5023, SiT5024, SiT3907, SiT3921, SiT3922, SiT3621, SiT3622, SiT3651, SiT3652

6L QFN 3.2 mm x 2.5 mm PACKAGE TABLE OF MATERIAL DECLARATION – Carsem

No.	Name of the Component	Material Type	Component Weight, mg	Materials Analysis (element)	CAS Number	Element Weight, mg	Element wt% of Component	Element wt % of Package
1	Leadframe	C194 Alloy	5.448	Copper	7440-50-8	5.3172480	97.60	32.12
				Iron	7439-89-6	0.1269384	2.33	0.77
				Zinc	7440-66-6	0.0038136	0.07	0.02
1a	Plating	NiPdAu	0.072	Nickel	7440-02-0	0.0670000	93.06	0.40
				Palladium	7440-05-3	0.0030000	4.17	0.02
				Gold	7440-57-5	0.0020000	2.78	0.01
2	Die 1	CMOS Die	1.075	Si	7440-21-3	1.0750000	100.00	6.49
3	Die 2	MEMS Die	0.082	Si	7440-21-3	0.0820000	100.00	0.50
4	Die attach material 1	Non-Conductive epoxy	0.171	Aluminium oxide	1344-28-1	0.0540000	31.58	0.33
				Carbinol acetate	112-15-2	0.0370000	21.64	0.22
				Epoxy Cresol Novolac Resin	29690-82-2	0.0310000	18.13	0.19
				CP Bisph. A diglycidyl ether+Bisph. A	25036-25-3	0.0170000	9.94	0.10
				Bisphenol A diglycidyl ether resin	25068-38-6	0.0090000	5.26	0.05
				Dapsone	80-08-0	0.0090000	5.26	0.05
				Additive	Proprietary	0.0140000	8.19	0.08
5	Die attach material 2	Conductive epoxy	0.030	Silver	7440-22-4	0.0222000	74.00	0.13
				Acrylate	Proprietary	0.0060000	20.00	0.04
				Resin	Proprietary	0.0009000	3.00	0.01
				Additive	Proprietary	0.0009000	3.00	0.01
6	Wire	Gold	0.155	Au	7440-57-5	0.1550000	100.00	0.94
7	Encapsulation	Epoxy Resin	9.520	Fused silica	60676-86-0	8.9126240	93.62	53.84
				Epoxy resin	Proprietary	0.2884560	3.03	1.74
				Phenol resin	Proprietary	0.2884560	3.03	1.74
				Carbon black	1333-86-4	0.0304640	0.32	0.18
Total Package Weight, mg:			16.553					

Revision History

Table 10: Revision History

Version	Description of Change	Reason for Change
A00	Initial Release	Created new document with Composition declaration tables for QFN packages for Encore products.
A01	Added 6LD 7.0X5.0 Type D package Table; updated 4LD 7.0X5.0 table for UTAC	Typo in 4LD 7.0X5.0 Table; 6LD 7.0X5.0 Type D package data are available from UTAC
A02	Added SiT9121/2, SiT3821/2, SiT5021/2, SiT5023/4, SiT3921/2, SiT3621/2, and SiT3651/2 products	Encore Differential products are released to production; customer requests
A03	Sec 1.2 added 2.7mm X 2.4mm package; added sec 3.9 and added Table-8	New package offering for Encore- 2.7mm X 2.4mm (package type G)
A04	Add SiT9120 in Sec 1.2, revised Table-6 and Table-7	SiT9120 is missing in the product list
A05	Fixed typo in all tables	Typo correction
A06	Revised sec 1.2, 3.1, added Table-9 and updated Table-1 to -8 with part list	6 QFN 3225 package is available; need to add SiT3907
A07	Revised Composition reports	Updated lists of P/N
A08	Adjusted Composition reports	Typo in tables
A09	Composition report changed	Bad quality of composition report
A10	Table-6 and Table-9 are updated	Material content was edited by subcon
A11	All Carsem's tables are updated	Material content was edited by subcon
A12	Table-8 updated	Wrong package size table shown
A13	Table-6, -7, -9 updated	SiT9156 added
A14	All tables updated Formatting update	Typo correction Formatting changes, Disclaimer changed

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